



JOC851 Series

Rev.A.1.0

DESCRIPTION:

The JOC851 series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a silicon planar high voltage phototransistor detector in a plastic DIP4 package with different lead forming options. With the robust coplanar double mold structure, JOC851 series provide the most stable isolation feature. The products are widely used in switch modepower supplies, programmable controllers, household appliances and office equipment.



MAIN FEATURES

Current transfer ratio (CTR: 50%-600% @ $I_F=5mA$, $V_{CE}=5V$)

High isolation voltage between input and output

($V_{iso}=5,000V_{rms}$)

Operating temperature up to +110°C

Collector-Emitter voltage $BV_{CEO} \geq 350V$

CQC approved

VDE approved

UL approved

RoHS & REACH Compliance

ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Parameter		Symbol	Value	Unit
Input	Forward Current	I_F	60	mA
	Peak Forward Current	I_{FP}	1 ^①	A
	Reverse Voltage	V_R	6	V
	Power Dissipation	P_D	100	mW
Output	Collector-emitter Voltage	V_{CEO}	350	V
	Emitter-collector Voltage	V_{ECO}	7	V
	Collector Current	I_C	50	mA
	Power Dissipation	P_C	150	mW
Total Power Dissipation		P_{tot}	200	mW
Isolation Voltage		V_{iso}	5000 ^②	Vrms
Operating Temperature		T_{opr}	-55~+110	°C

Storage Temperature	T _{stg}	-55~+125	°C
Soldering Temperature	T _{sol}	260	°C


NOTE1: 100μs pulse, 100Hz frequency

NOTE2: AC for 1minute, R.H.=40~60%

ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V _F	I _F =10mA	-	1.24	1.4	V
			I _F =20mA	-	1.3	1.5	
	Reverse Current	I _R	V _R =6V	-	-	1	μA
	Terminal Capacitance	C _t	V=0, f=1MHz	-	30	250	pF
Output	Collector-Emitter dark current	I _{CEO}	V _{CE} =200V, I _F =0	-	-	100	nA
	Collector-Emitter breakdown voltage	BV _{CEO}	I _C =0.1mA I _F =0	350	-	-	V
	Emitter-Collector breakdown voltage	BV _{ECO}	I _E =0.1mA I _F =0	7	-	-	V
Transfer Characteristics	Current transfer ratio	CTR ^①	I _F =5mA V _{CE} =5V	50	-	600	%
	Collector-Emitter Saturation Voltage	V _{CE(sat)}	I _F =20mA I _C =1mA	-	0.06	0.2	V
	Isolation resistance	R _{IO}	DC500V 40~60%R.H.	5×10 ¹⁰	10 ¹¹	-	Ω
	Floating Capacitance	C _{IO}	V=0, f=1MHz	-	0.6	1	pF
	Cut-off Frequency	f _c	V _{CE} =5V, I _C =2mA R _L =100Ω, -3dB	-	80	-	kHz
	Rise Time	t _r	V _{CE} =2V, I _C =2mA R _L =100Ω	-	3	18	μs
	Fall Time	t _f		-	4	18	μs
	Response Time	t _{on}		-	5	25	μs
t _{off}		-		4	25	μs	

ORDERING AND MARKING INFORMATION

MARKING INFORMATION			
		JOC : Company Abbr. 851 : Part Number V : VDE Option Y : Fiscal Year A : Manufacturing Code WW : Work Week	
ORDERING INFORMATION			
JOC851(Y)(Z)-GV			
JOC – Company Abbr. 851 – Part Number Y – Lead Form Option (M/S/SL/SLM/None) Z – Tape and Reel Option (T1/T2/T3/T4) G – Green V – VDE Option (V or None)			
Packing Quantity			
Option	Quantity	Quantity – Inner box	Quantity –Outer box
None/M	100 Units/Tube	32 Tubes/Inner box	10 Inner box/Outer box =32k Units
S(T1/T2)	1500 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box =22.5k Units
S(T3/T4)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box =15k Units
SL(T1/T2)	1500 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box =22.5k Units
SL(T3/T4)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box =15k Units
SLM(T1/T2)	1500 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box =22.5k Units

Characteristics Curves

FIG.1: Forward Current vs. Ambient Temperature

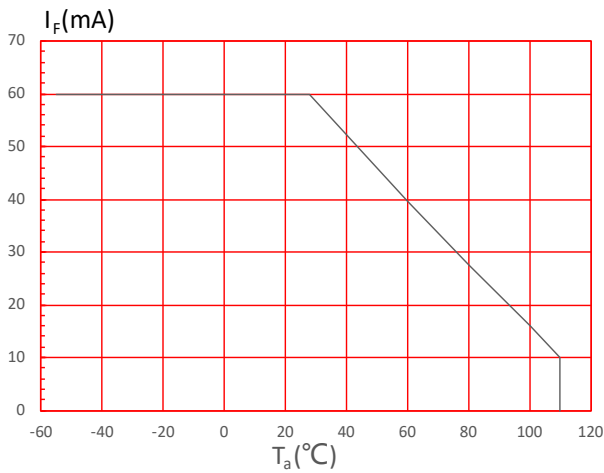


FIG.2: Collector Power Dissipation vs. Ambient Temperature

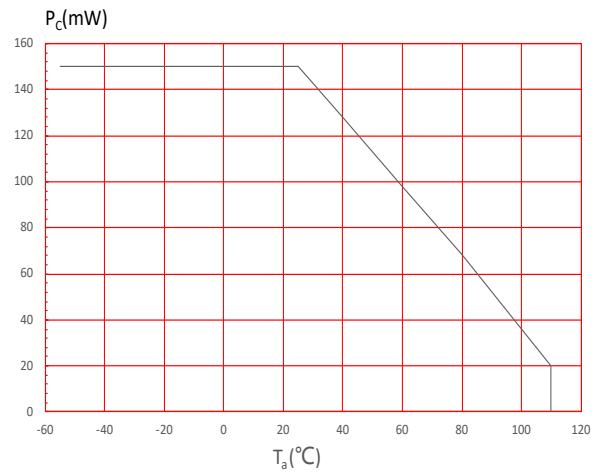


FIG.3: Forward Current vs. Forward Voltage

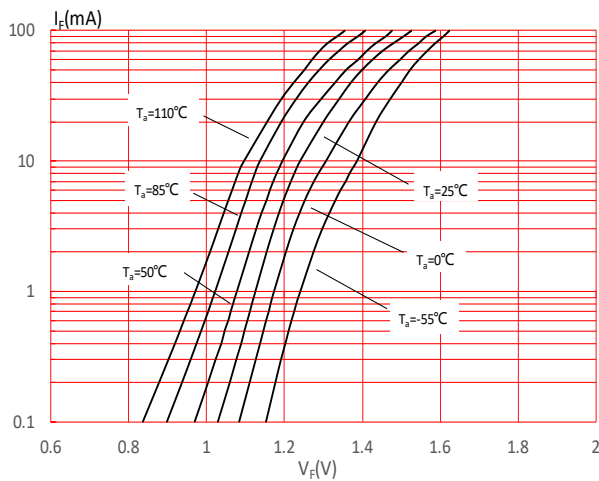


FIG.4: Normalized Collector Dark Current vs. Ambient Temperature

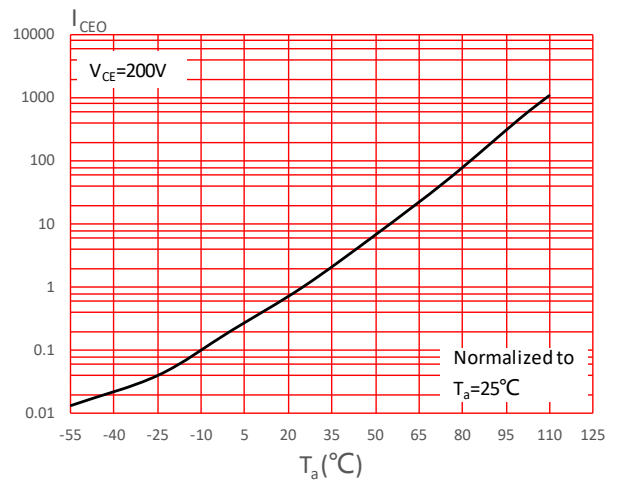


FIG.5: Collector Current vs. Collector-emitter Voltage

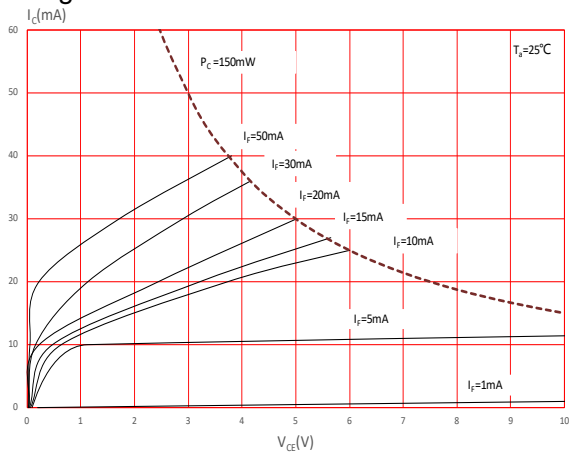


FIG.6: Normalized Current Transfer Ratio vs. Forward Current

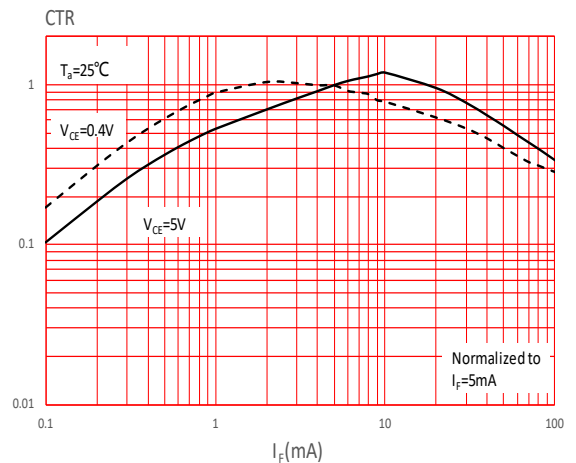


FIG.7: Normalized Current Transfer Ratio vs. Ambient Temperature

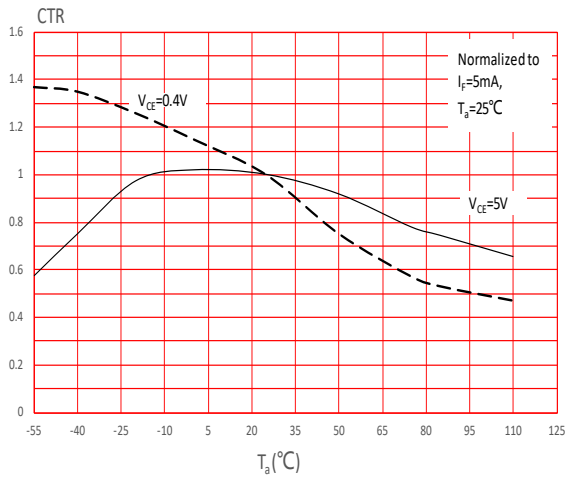


FIG.8: Normalized Collector-emitter Saturation Voltage vs. Ambient Temperature

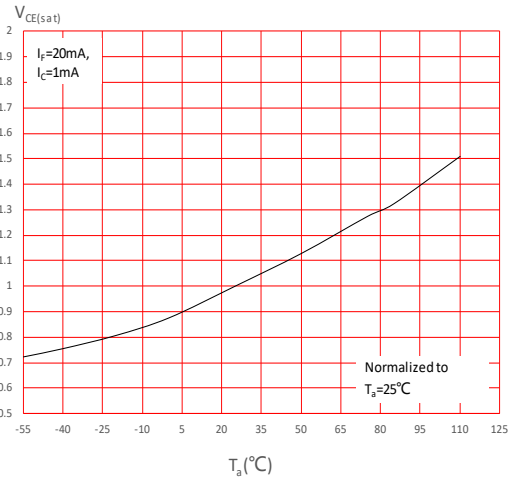


FIG.9: Response Time vs. Load Resistance

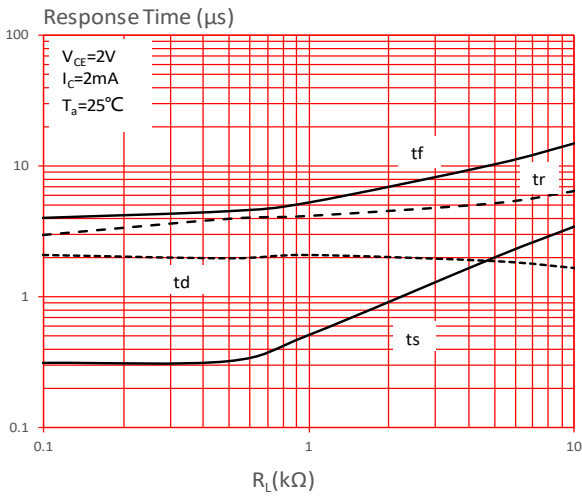
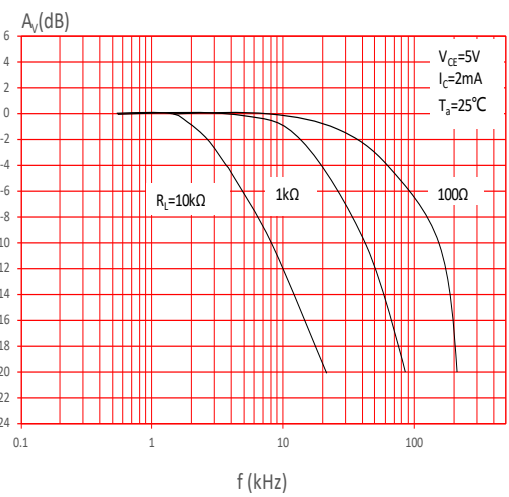


FIG.10: Frequency Response



Test Circuits

FIG.11: Test Circuits of Response Time

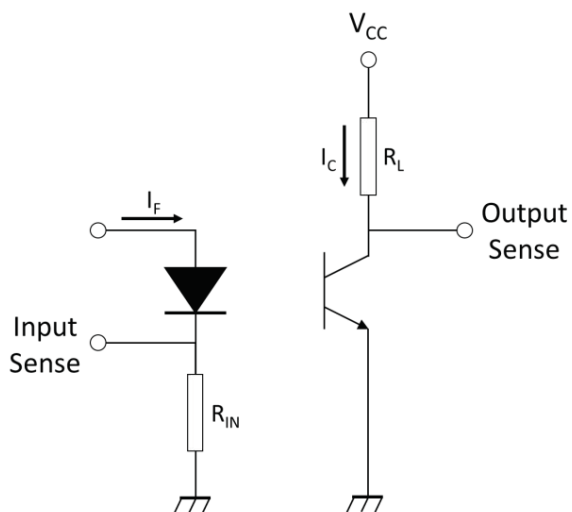


FIG.12: Curves of Response Time

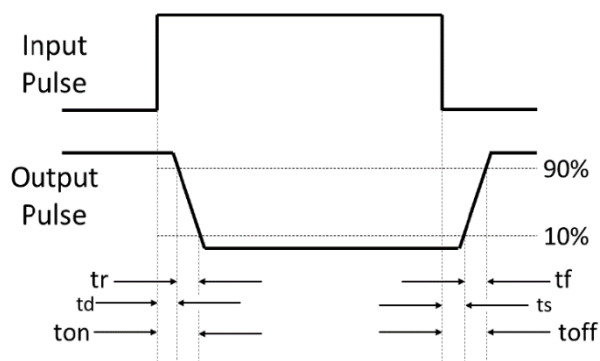
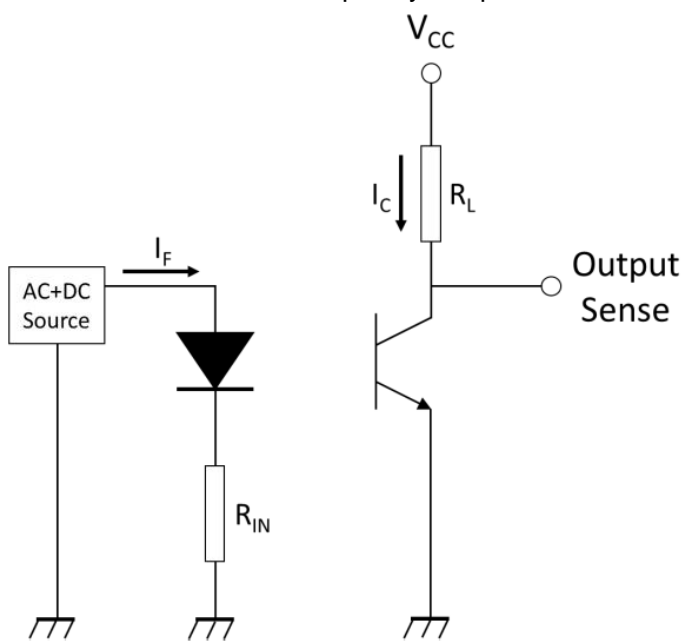
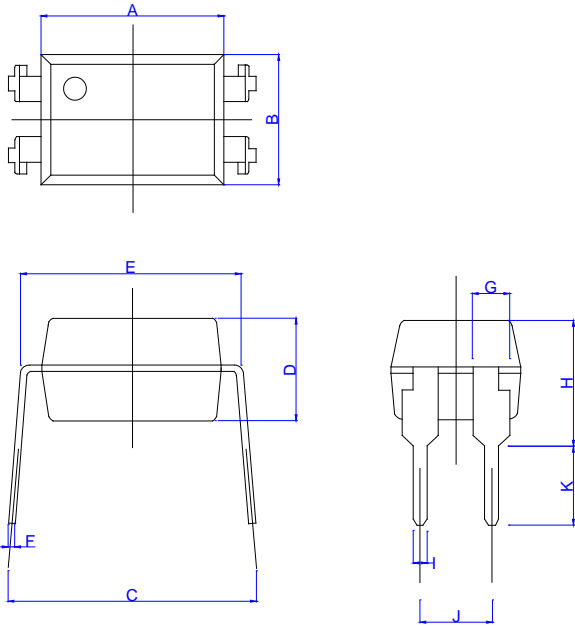


FIG.13: Test Circuits of Frequency Response



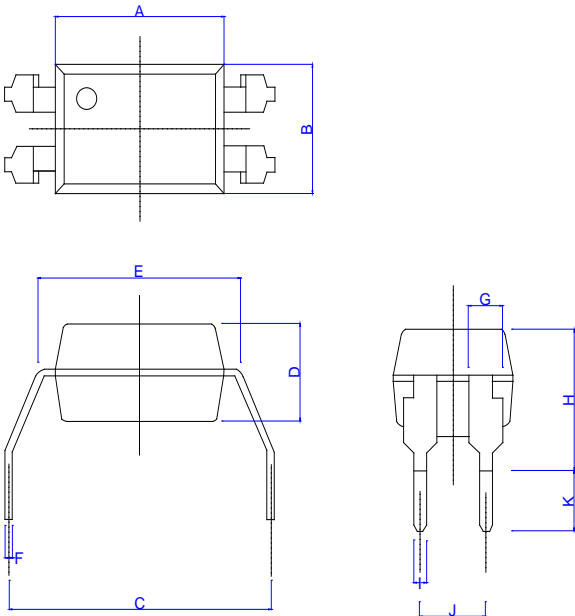
Package Dimension (Unit: mm)

Standard DIP Type:



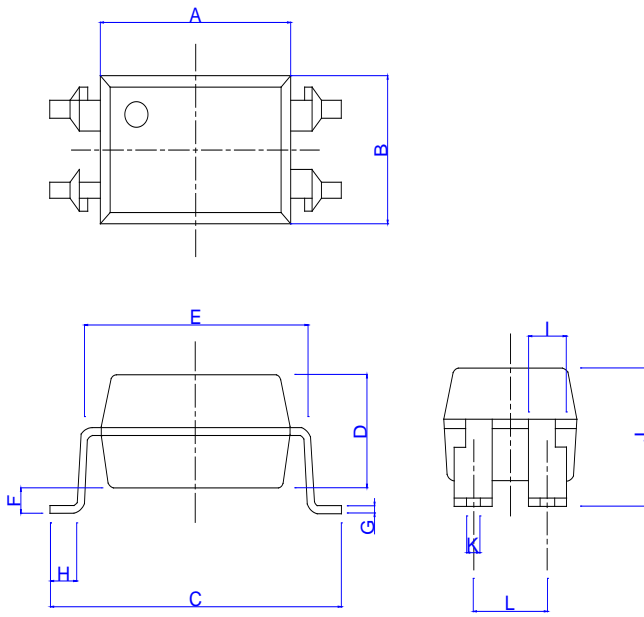
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.00		7.00	0.236		0.276
B	4.08		5.08	0.161		0.200
C	7.62		10.16	0.300		0.400
D	3.00		4.00	0.118		0.157
E	7.32		7.92	0.288		0.312
F	0.15		0.36	0.006		0.014
G	0.90		1.50	0.035		0.059
H	3.50		4.80	0.138		0.189
I	0.40		0.60	0.016		0.024
J	2.29		2.79	0.090		0.110
K	2.45		3.50	0.096		0.138

Option M Type:



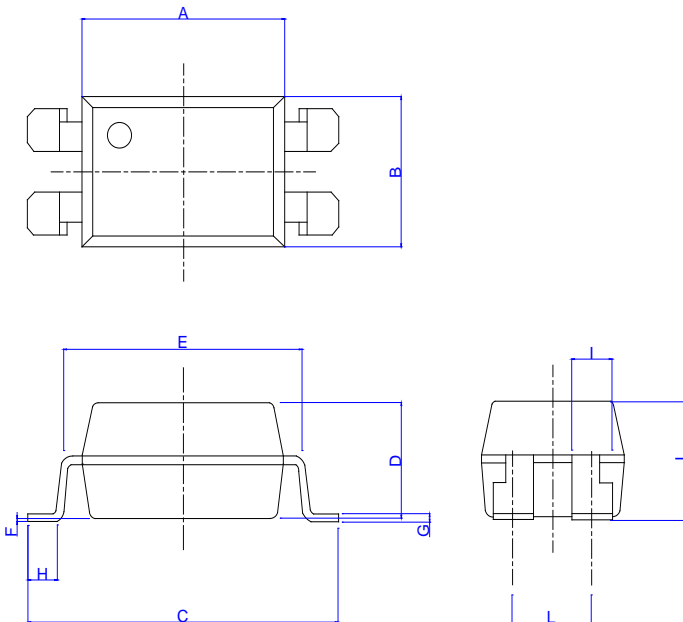
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.80	0.244		0.268
B	4.10		4.90	0.161		0.193
C	9.66		10.66	0.380		0.420
D	3.00		4.00	0.118		0.157
E	7.32		7.92	0.288		0.312
F	0.15		0.36	0.006		0.014
G	0.90		1.50	0.036		0.059
H	4.16		4.88	0.164		0.192
I	0.40		0.60	0.016		0.024
J	2.29		2.79	0.090		0.110
K	2.00		2.70	0.079		0.106

Option S Type:



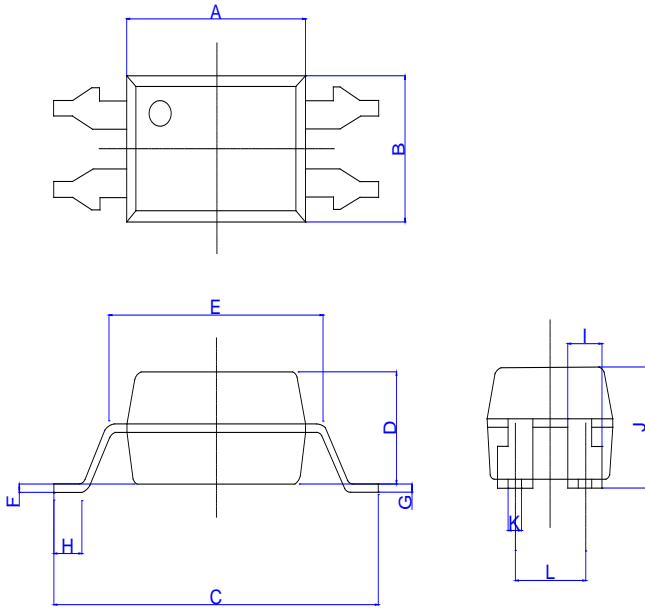
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.80	0.244		0.268
B	4.30		4.90	0.169		0.193
C	9.86		10.50	0.388		0.413
D	3.20		3.80	0.126		0.150
E	7.32		7.92	0.288		0.312
F	0.00		1.00	0.000		0.039
G	0.15		0.35	0.006		0.014
H	0.50		1.10	0.020		0.043
I	1.10		1.50	0.043		0.059
J	3.50		4.80	0.138		0.189
K	0.40		0.60	0.016		0.024
L	2.29		2.79	0.090		0.110

Option SL Type:



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.00		7.00	0.236		0.276
B	4.08		5.08	0.161		0.200
C	9.50		10.50	0.374		0.413
D	3.00		4.00	0.118		0.157
E	7.32		7.92	0.288		0.312
F	0.00		0.60	0.000		0.024
G	0.15		0.36	0.006		0.014
H	0.50		1.40	0.020		0.055
I	0.90		1.50	0.035		0.059
J	3.20		4.35	0.126		0.171
L	2.29		2.79	0.090		0.110

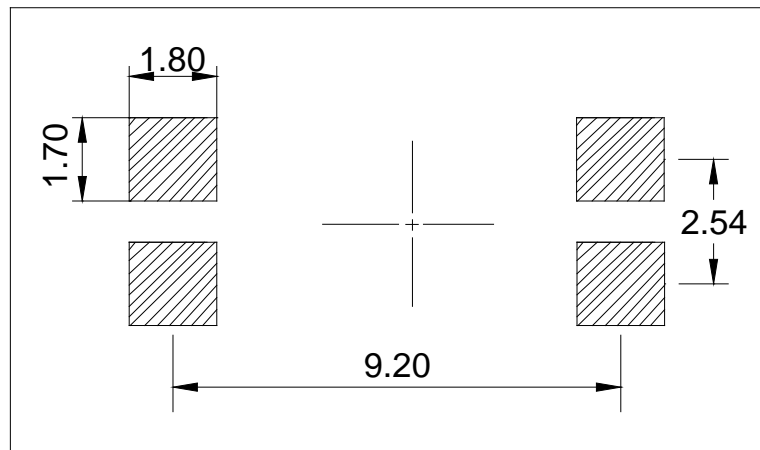
Option SLM Type:



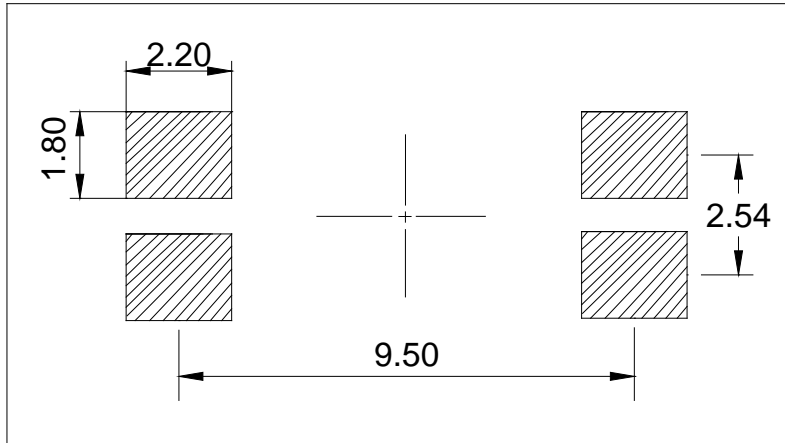
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.30		6.70	0.248		0.264
B	4.38		4.78	0.172		0.188
C	11.60		12.10	0.457		0.476
D	3.30		3.70	0.130		0.146
E	7.32		7.92	0.288		0.312
F	0.00		0.30	0.000		0.012
G	0.20		0.30	0.008		0.012
H	0.50		0.90	0.020		0.035
I	1.15		1.35	0.045		0.053
J	3.45		3.85	0.136		0.152
K	0.45		0.55	0.018		0.022
L	2.34		2.74	0.092		0.108

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

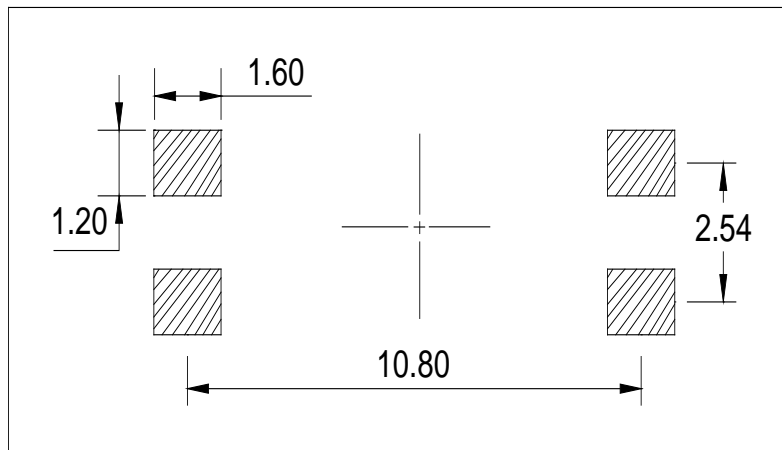
Option S



Option SL

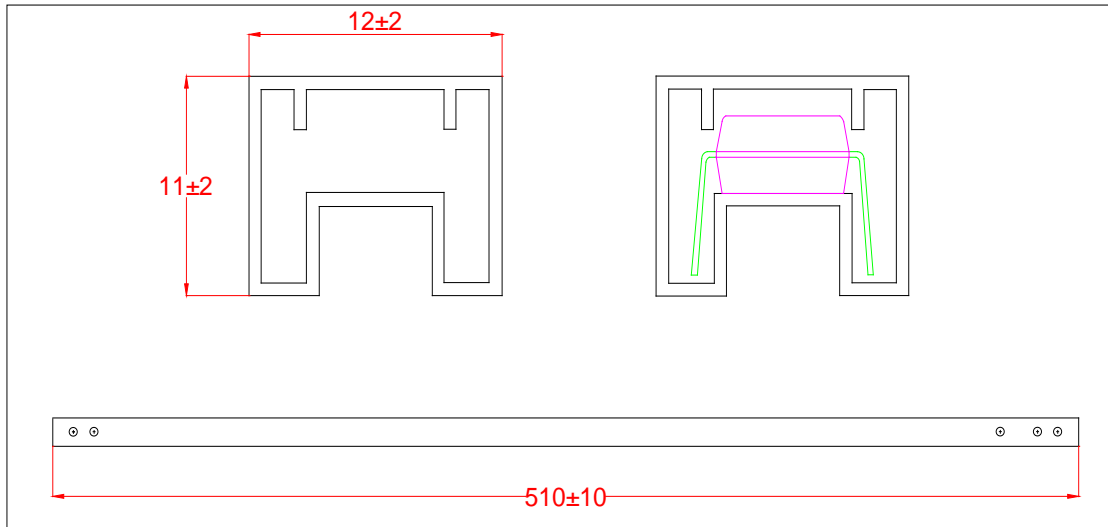


Option SLM

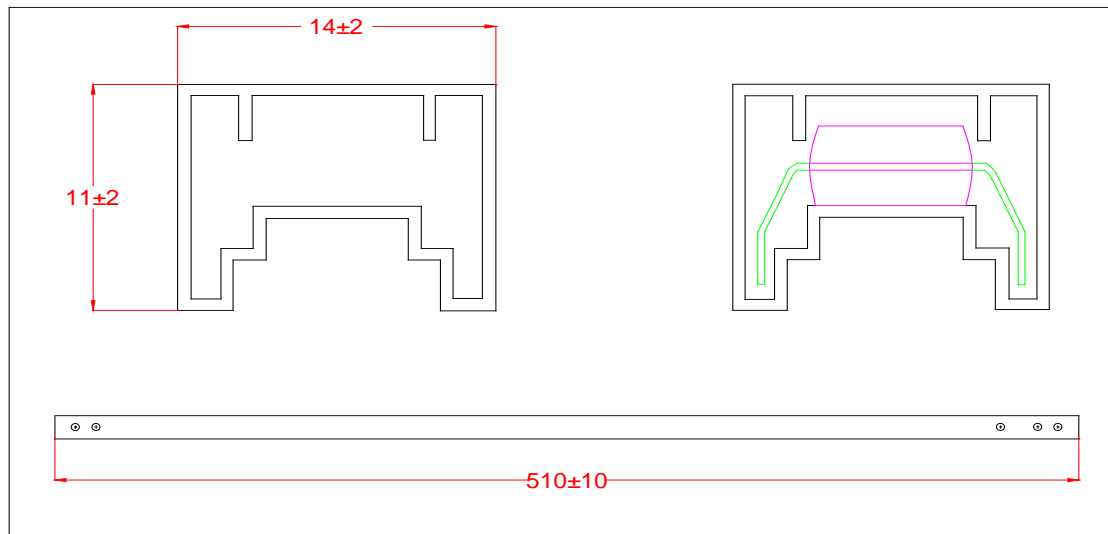


TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Standard DIP

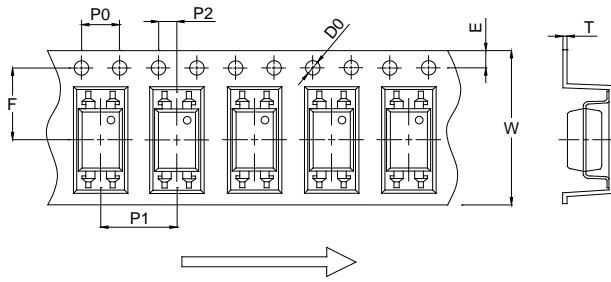


Option M

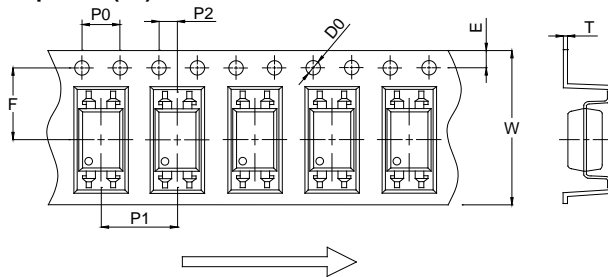


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option S(T1)

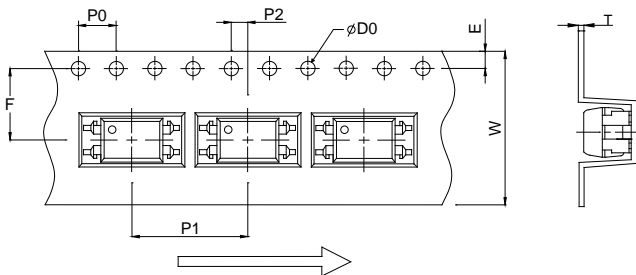


Option S(T2)

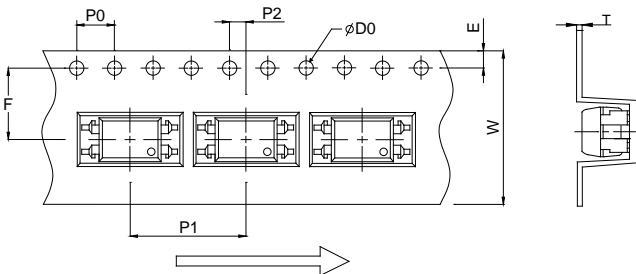


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.65		0.059	0.065
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.30	0.40	0.50	0.012	0.016	0.020
W	15.70	16.00	16.30	0.618	0.630	0.642

Option S(T3)

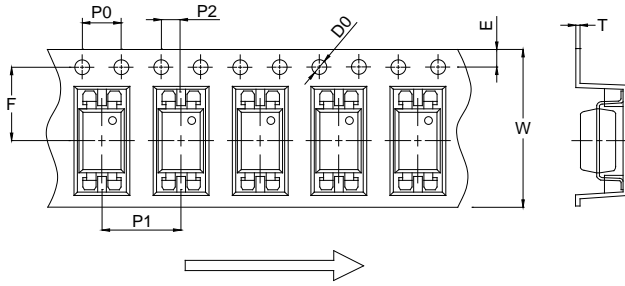


Option S(T4)



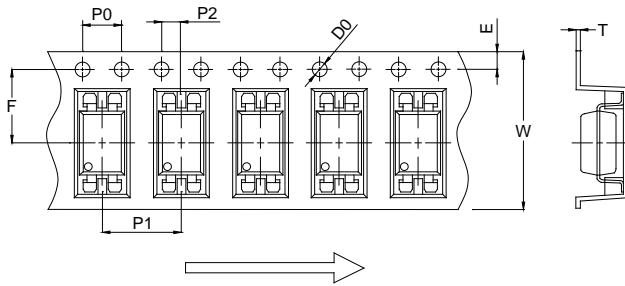
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.65		0.059	0.065
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.30	0.40	0.50	0.012	0.016	0.020
W	15.70	16.00	16.30	0.618	0.630	0.642

Option SL(T1)

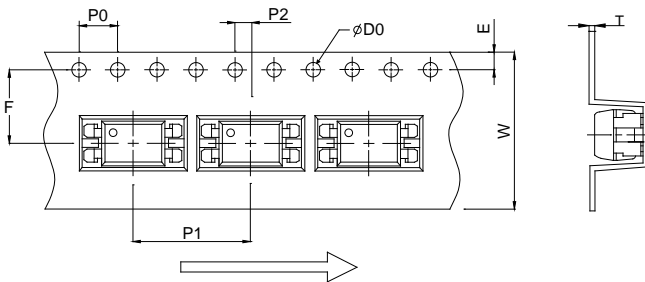


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.065
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.70	16.00	16.30	0.618	0.630	0.642

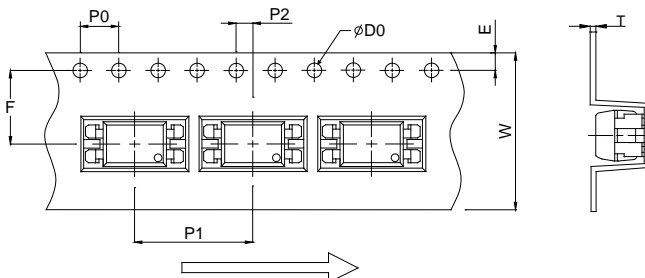
Option SL(T2)



Option SL(T3)

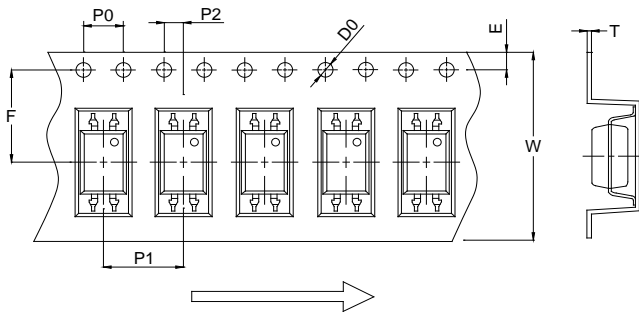


Option SL(T4)

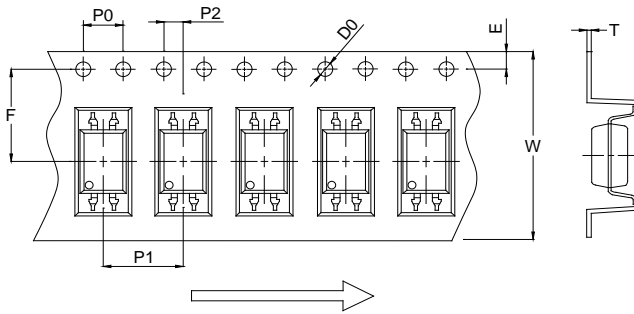


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.45	0.55	0.014	0.018	0.022
W	15.70	16.00	16.30	0.618	0.630	0.642

Option SLM(T1)

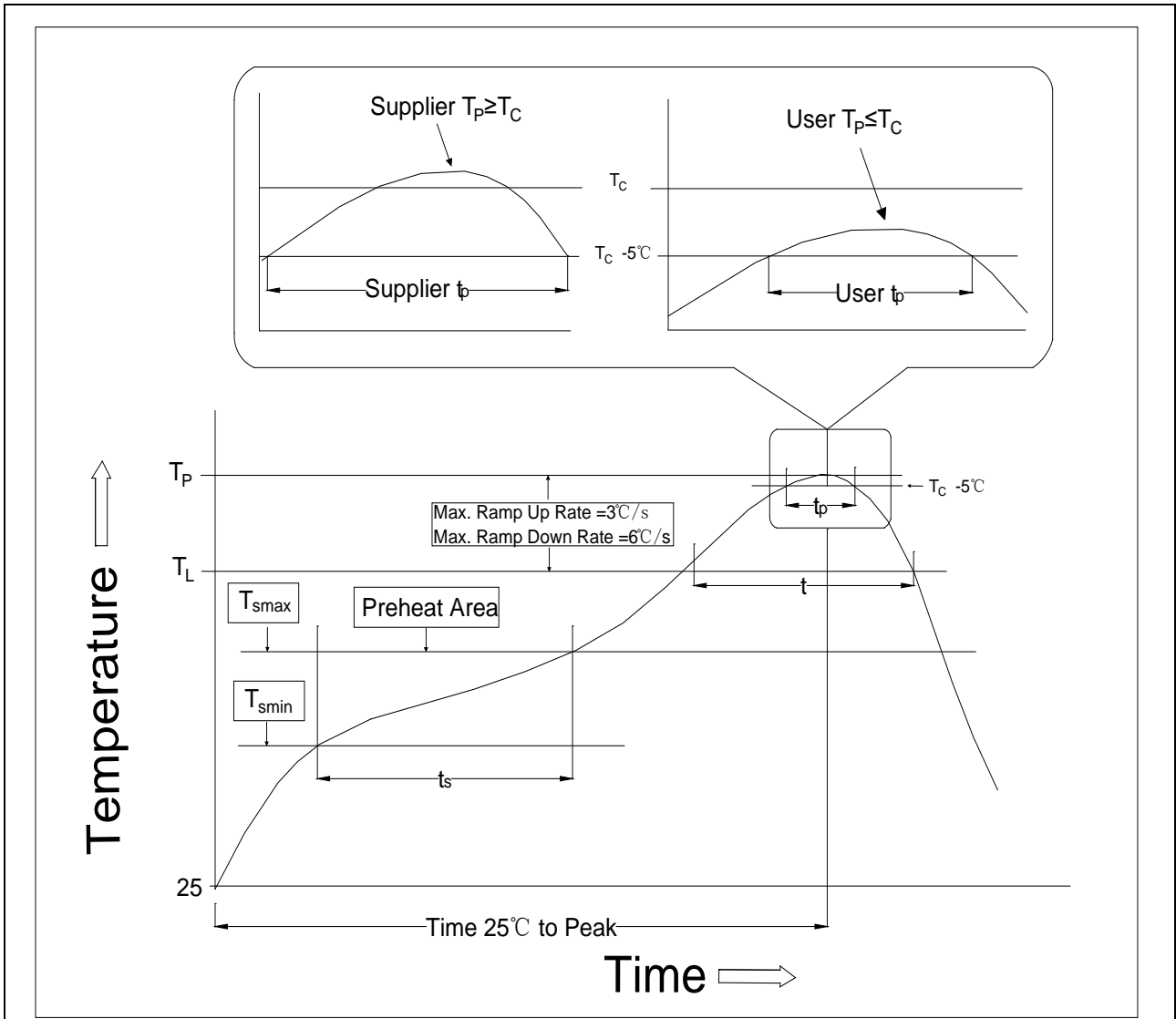


Option SLM(T2)



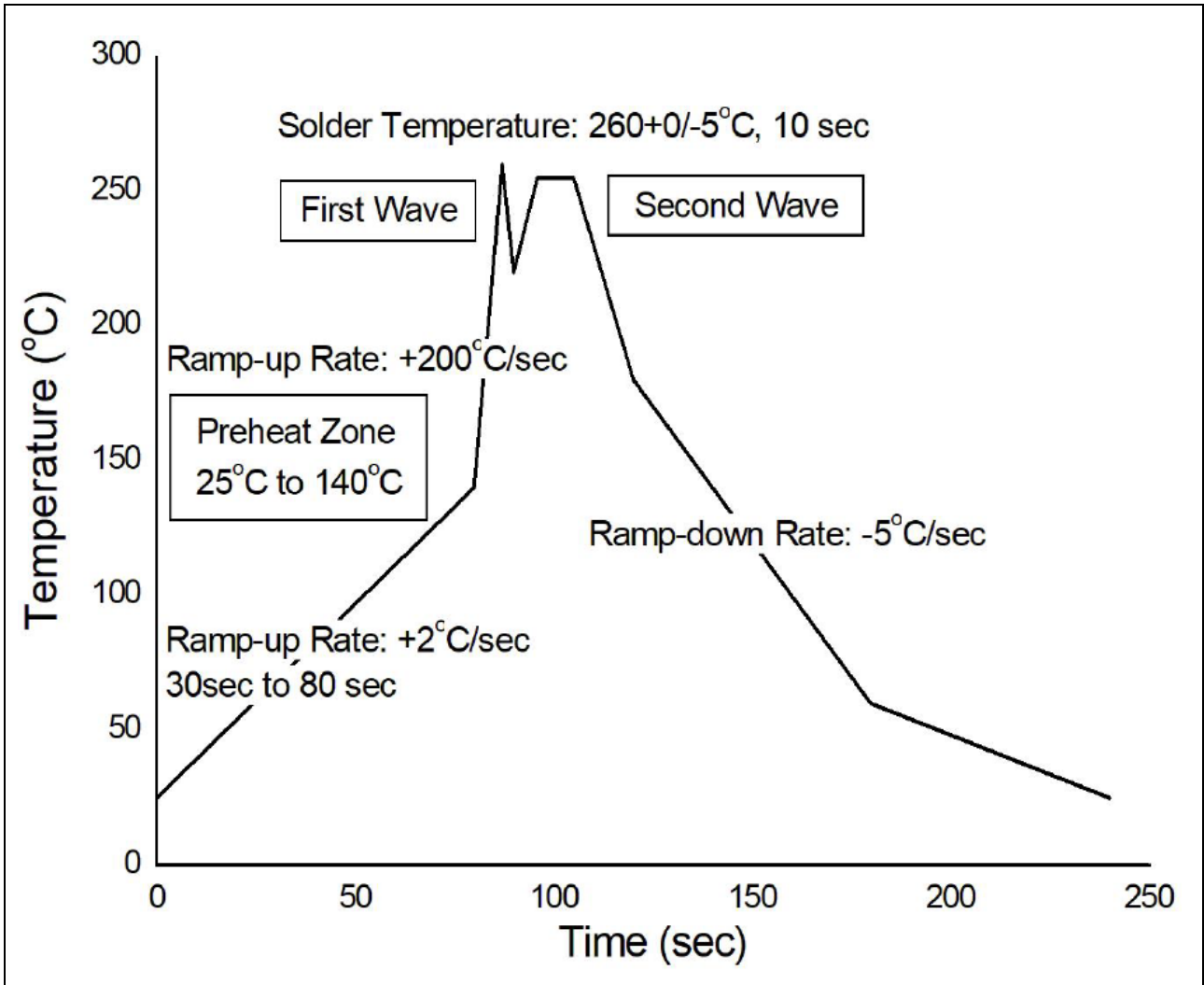
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	11.45	11.50	11.55	0.451	0.453	0.455
T	0.35	0.40	0.45	0.014	0.016	0.018
W	23.70	24.00	24.30	0.933	0.945	0.957

REFLOW INFORMATION



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	100	150°C
Temperature Max. (T _{smax})	150	200°C
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds	60-120 seconds
Ramp-up Rate (t _L to t _P)	3°C/second max.	3°C/second max.
Liquidus Temperature (T _L)	183°C	217°C
Time (t _L) Maintained Above (T _L)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235°C+0°C/-5°C	260°C+0°C/-5°C
Time (t _P) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON

Soldering Temperature	360±5°C
Soldering Time	3s max.

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